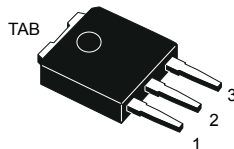
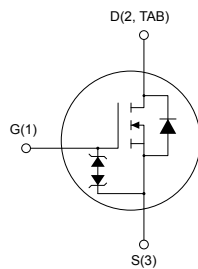


N-channel 700 V, 1.2 Ω typ., 3.5 A MDmesh™ M6 Power MOSFET in a short IPAK package



Short IPAK



AM01475V1

Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STU5N70M6-S	700 V	1.4 Ω	3.5 A

- Reduced switching losses
- Lower $R_{DS(on)}$ per area vs previous generation
- Low gate input resistance
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

The new MDmesh™ M6 technology incorporates the most recent advancements to the well-known and consolidated MDmesh family of SJ MOSFETs. STMicroelectronics builds on the previous generation of MDmesh devices through its new M6 technology, which combines excellent $R_{DS(on)}$ per area improvement with one of the most effective switching behaviors available, as well as a user-friendly experience for maximum end-application efficiency.

Product status link

[STU5N70M6-S](#)

Product summary

Order code	STU5N70M6-S
Marking	5N70M6
Package	Short IPAK
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	3.5	A
	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	2.2	A
$I_{DM}^{(1)}$	Drain current pulsed	8	A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	45	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	5	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	
T_j	Operating junction temperature range	-55 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature range		

1. Pulse width limited by safe operating area
2. $I_{SD} \leq 3.5\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DS\text{ peak}} \leq V_{(BR)DSS}$, $V_{DD} = 100\text{ V}$
3. $V_{DS} \leq 560\text{ V}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-case}}$	Thermal resistance junction-case	2.78	$^\circ\text{C}/\text{W}$
$R_{thj\text{-amb}}$	Thermal resistance junction-ambient	100	$^\circ\text{C}/\text{W}$

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by $T_{j\text{max}}$)	1	A
E_{AS}	Single-pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	77	mJ

2 Electrical characteristics

$T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified

Table 4. On-/off-states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	700			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}, V_{DS} = 700\text{ V}$			1	μA
		$V_{GS} = 0\text{ V}, V_{DS} = 700\text{ V}$ $T_C = 125\text{ }^\circ\text{C}^{(1)}$			100	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}, V_{GS} = \pm 25\text{ V}$			± 5	μA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.25	3	3.75	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}, I_D = 1.75\text{ A}$		1.2	1.4	Ω

1. Defined by design, no subject to production test.

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$	-	170	-	pF
C_{oss}	Output capacitance		-	15	-	pF
C_{riss}	Reverse transfer capacitance		-	1	-	pF
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }560\text{ V}, V_{GS} = 0\text{ V}$	-	70	-	pF
R_g	Intrinsic gate resistance	$f = 1\text{ MHz},$ open drain	-	5	-	Ω
Q_g	Total gate charge	$V_{DD} = 350\text{ V}, I_D = 1\text{ A}$	-	5.1	-	nC
Q_{gs}	Gate-source charge	$V_{GS} = 0\text{ to }10\text{ V}$	-	0.85	-	nC
Q_{gd}	Gate-drain charge	(see Figure 14. Test circuit for gate charge behavior)	-	2.6	-	nC

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 350\text{ V}, I_D = 1.75\text{ A},$ $R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	5.8	-	ns
t_r	Rise time		-	6.5	-	ns
$t_{d(off)}$	Turn-off delay time		-	17	-	ns
t_f	Fall time		-	27.5	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		3.5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		8	A
$V_{SD}^{(2)}$	Forward on-voltage	$I_{SD} = 3.5 \text{ A}$, $V_{GS} = 0 \text{ V}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 3.5 \text{ A}$, $V_{DD} = 60 \text{ V}$, $di/dt = 100 \text{ A}/\mu\text{s}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	230		ns
Q_{rr}	Reverse recovery charge		-	1.25		μC
I_{RRM}	Reverse recovery current	$I_{SD} = 3.5 \text{ A}$, $V_{DD} = 60 \text{ V}$, $di/dt = 100 \text{ A}/\mu\text{s}$, $T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	11		A
t_{rr}	Reverse recovery time		-	277		ns
Q_{rr}	Reverse recovery charge		-	1.4		μC
I_{RRM}	Reverse recovery current		-	10		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

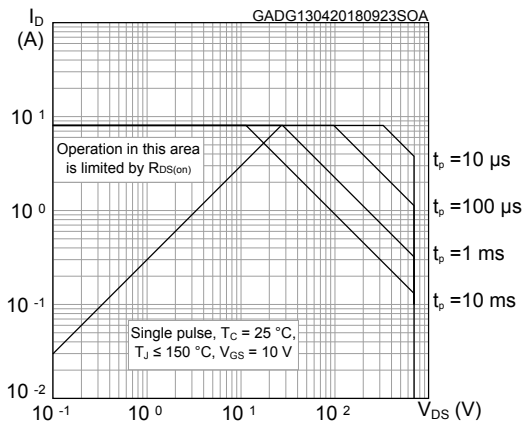


Figure 2. Thermal impedance

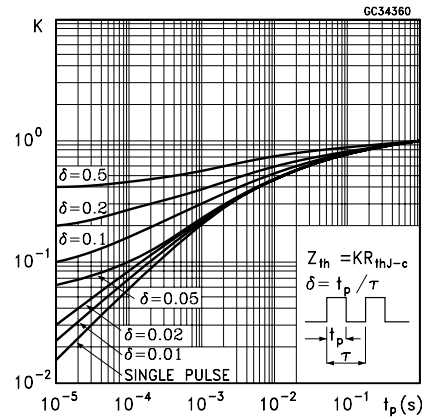


Figure 3. Output characteristics

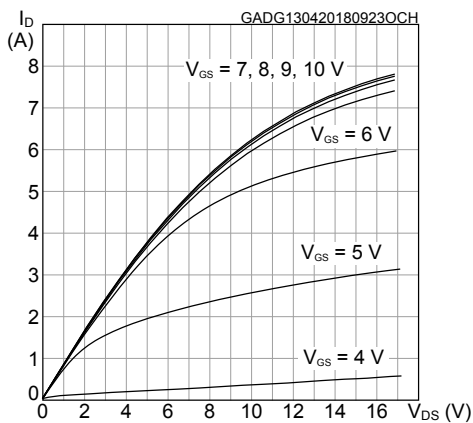


Figure 4. Transfer characteristics

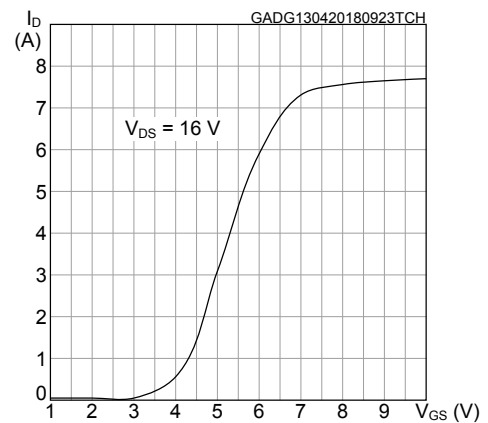


Figure 5. Gate charge vs gate-source voltage

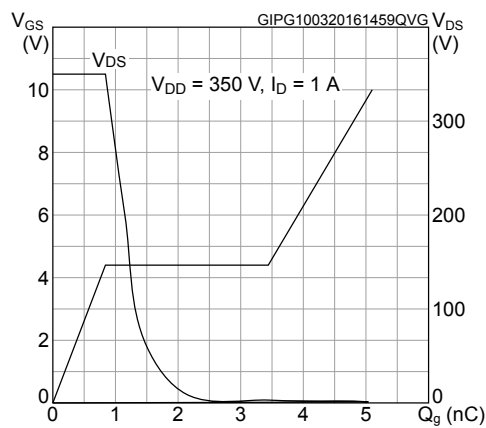


Figure 6. Static drain-source on-resistance

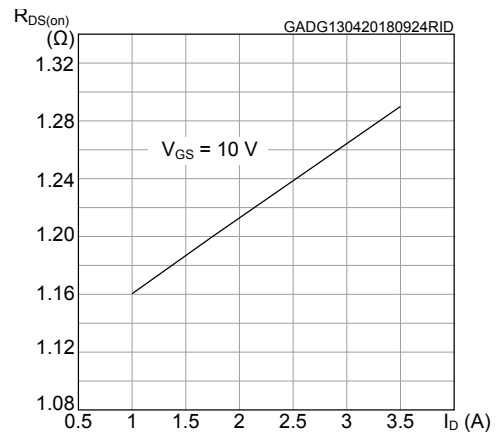


Figure 7. Capacitance variations

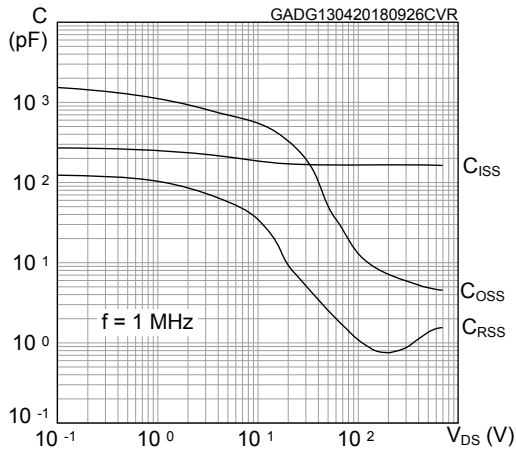


Figure 8. Normalized gate threshold voltage vs temperature

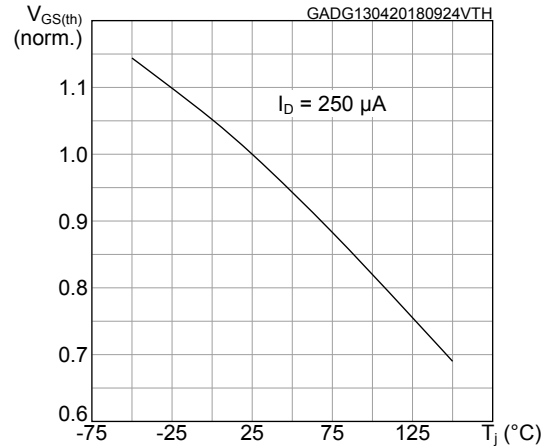


Figure 9. Normalized on-resistance vs temperature

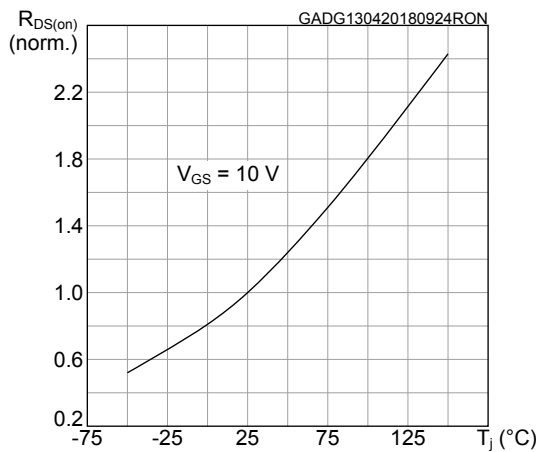


Figure 10. Normalized V_(BR)DSS vs temperature

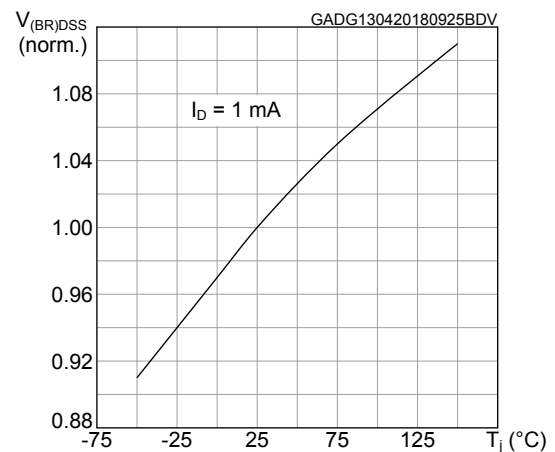


Figure 11. Output capacitance stored energy

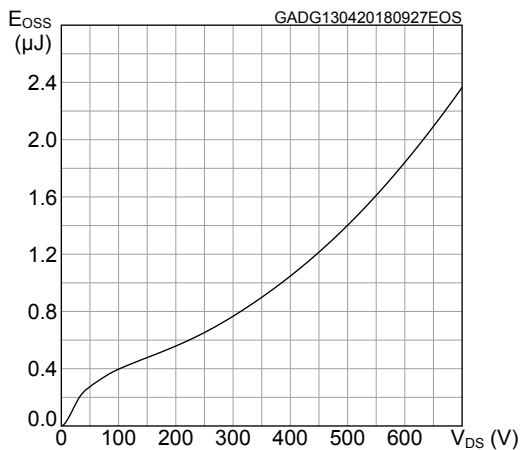
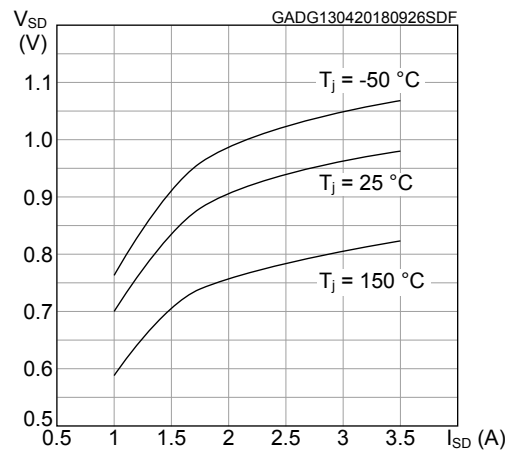
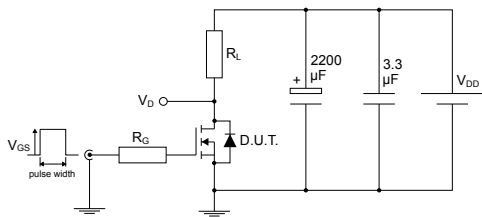


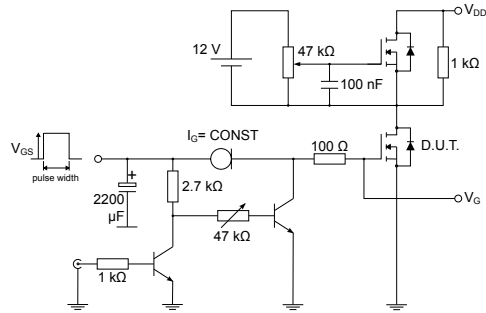
Figure 12. Source-drain forward characteristics



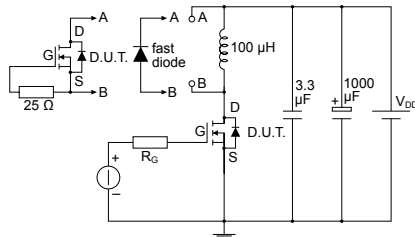
3 Test circuits

Figure 13. Test circuit for resistive load switching times


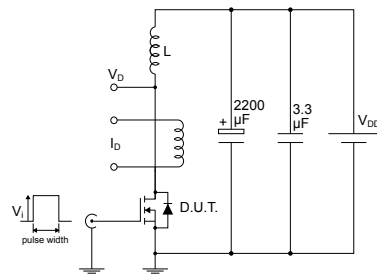
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Figure 14. Test circuit for gate charge behavior


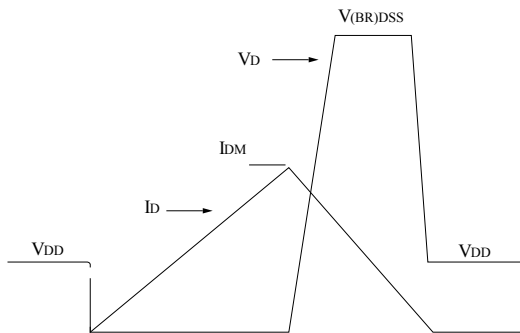
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Figure 15. Test circuit for inductive load switching and diode recovery times


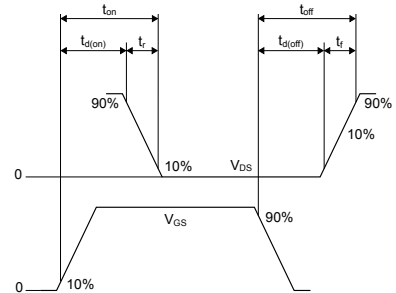
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Figure 16. Unclamped inductive load test circuit


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Figure 17. Unclamped inductive waveform


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Figure 18. Switching time waveform


AM01473v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 Short IPAK package information

Figure 19. Short IPAK package outline

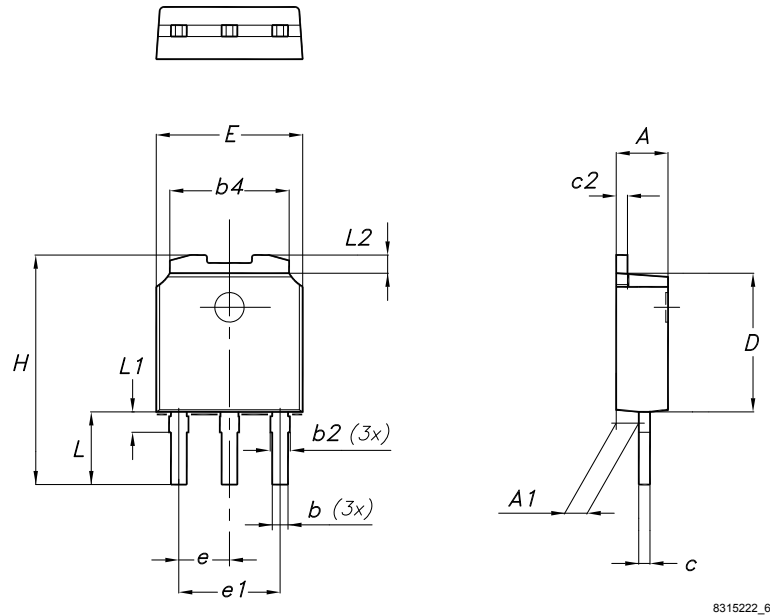


Table 8. Short IPAK package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.35
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.15
E	6.40		6.55
e		2.25	
e1	4.40		4.60
H	9.80		10.40
L	3.00		3.40
L1	0.80		1.20
L2		0.80	1.00

Revision history

Table 9. Document revision history

Date	Version	Changes
09-May-2018	1	Initial release. The document status is production data.

Contents

1	Electrical ratings	2
2	Electrical characteristics	3
2.1	Electrical characteristics (curves)	5
3	Test circuits	7
4	Package information	8
4.1	Short IPAK package information	9
	Revision history	10

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